



**GP**  
**ELECTRONICS**

**GP2367**

**20V P-Channel MOSFET**

### Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	$I_D$
-20V	44m $\Omega$ @-4.5V	-3.2A
	64m $\Omega$ @-2.5V	

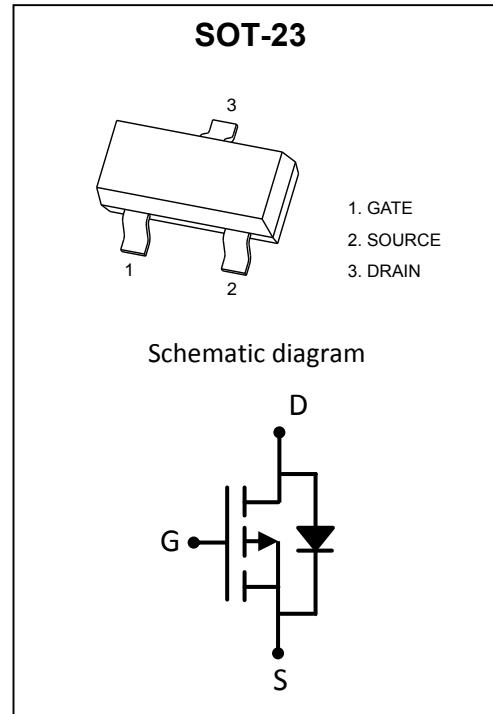
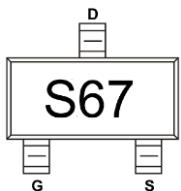
### Feature

- TrenchFET Power MOSFET
- Excellent  $R_{DS(on)}$  and Low Gate Charge

### Application

- DC/DC Converter
- Load Switch for Portable Devices
- Battery Switch

### MARKING:



### ABSOLUTE MAXIMUM RATINGS ( $T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	-20	V
Gate-Source Voltage	$V_{GS}$	$\pm 8$	V
Continuous Drain Current	$I_D$	-3.2 <sup>a</sup>	A
Pulsed Drain Current ( $t=300\mu\text{s}$ )	$I_{DM}$	-10	A
Power Dissipation	$P_D$	1.3 <sup>b</sup>	W
Thermal Resistance from Junction to Ambient	$R_{\theta JA}$	96 <sup>b</sup>	°C/W
Junction Temperature	$T_J$	150	°C
Storage Temperature	$T_{STG}$	-55~+150	°C

a. Device mounted on FR-4 substrate board, with minimum recommended pad layout, single side.

b. Device mounted on no heat sink.

**MOSFET ELECTRICAL CHARACTERISTICS(T<sub>a</sub>=25°C unless otherwise noted)**

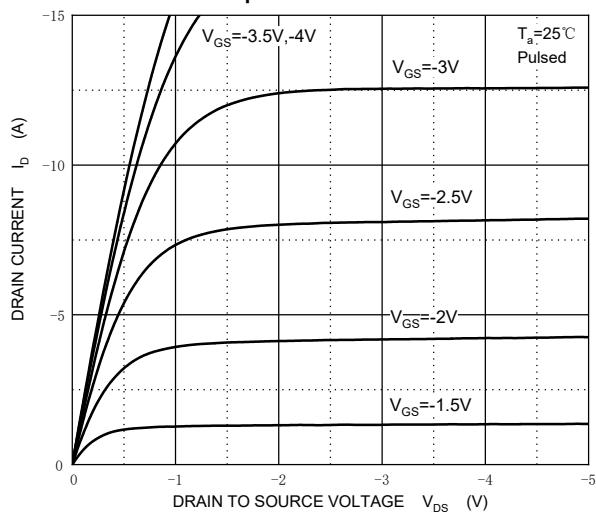
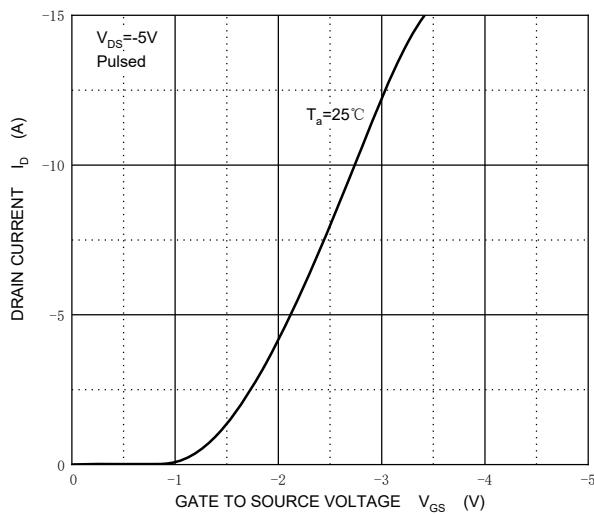
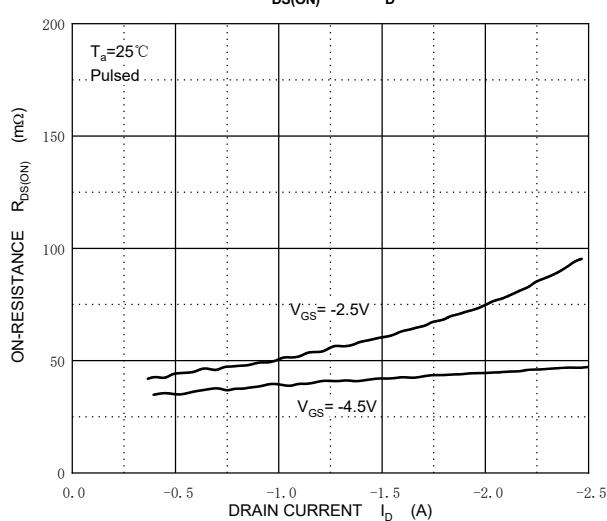
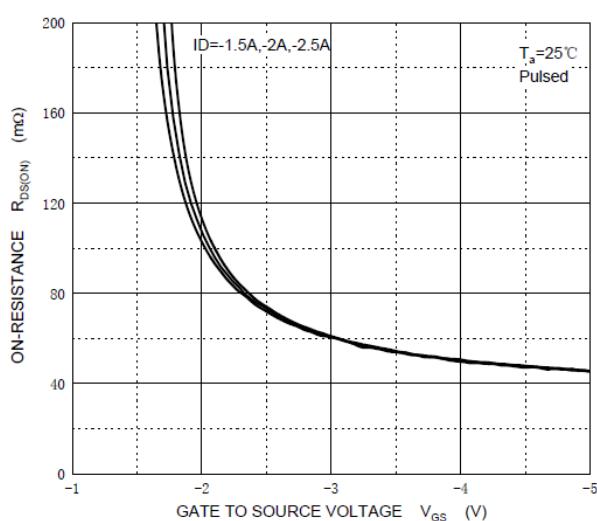
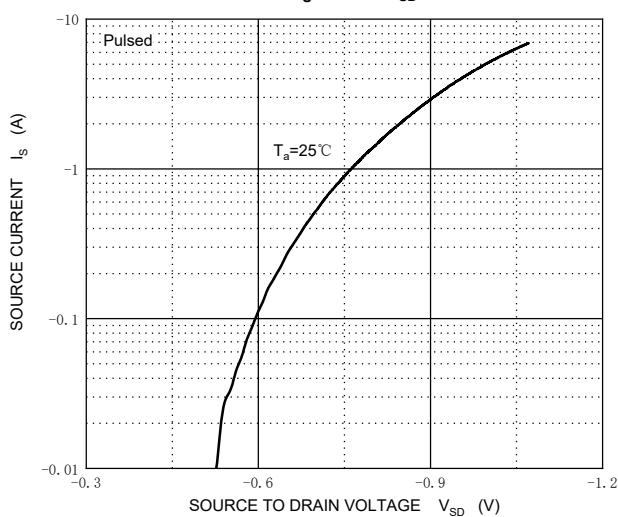
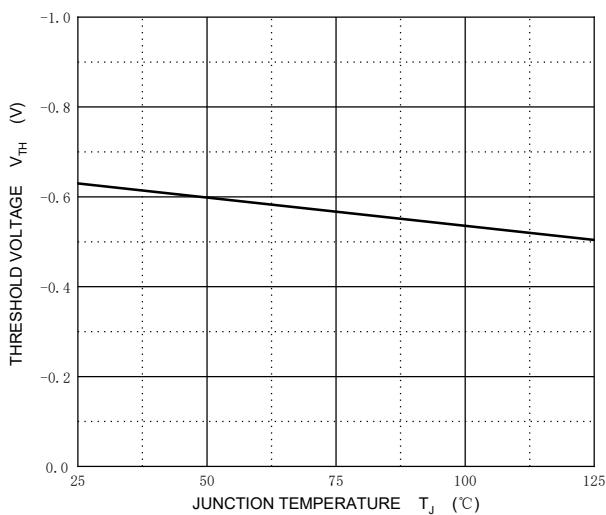
Parameter	Symbol	Test Condition	Min	Type	Max	Unit
<b>Static Characteristics</b>						
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = -250μA	-20			V
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = -20V, V <sub>GS</sub> = 0V			-100	nA
Gate-body leakage current	I <sub>GSS</sub>	V <sub>GS</sub> = ±8V, V <sub>DS</sub> = 0V			±100	nA
Gate threshold voltage <sup>a</sup>	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250μA	-0.4	-0.7	-1	V
Drain-source on-resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -2.5A		44	57	mΩ
		V <sub>GS</sub> = -2.5V, I <sub>D</sub> = -2.0A		64	95	
Forward transconductance <sup>a</sup>	g <sub>FS</sub>	V <sub>DS</sub> = -5V, I <sub>D</sub> = -5A	3			S
<b>Dynamic characteristics<sup>b</sup></b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> = -10V, V <sub>GS</sub> = 0V, f = 1MHz		548		pF
Output Capacitance	C <sub>oss</sub>			96		
Reverse Transfer Capacitance	C <sub>rss</sub>			89		
Gate resistance	R <sub>g</sub>	f = 1MHz		45	50	Ω
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> = -6V, V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -5A		10		nC
Gate-Source Charge	Q <sub>gs</sub>			1.7		
Gate-Drain Charge	Q <sub>gd</sub>			2.6		
Turn-on delay time	t <sub>d(on)</sub>	V <sub>DD</sub> = -6V, V <sub>GEN</sub> = -4.5V, I <sub>D</sub> = -4A R <sub>L</sub> = 6Ω, R <sub>GEN</sub> = 1Ω		26	40	ns
Turn-on rise time	t <sub>r</sub>			24	40	
Turn-off delay time	t <sub>d(off)</sub>			45	75	
Turn-off fall time	t <sub>f</sub>			18	20	
<b>Source-Drain Diode characteristics</b>						
Diode forward current	I <sub>s</sub>	T <sub>c</sub> = 25°C			-1.5	A
Diode pulsed forward current	I <sub>sM</sub>				-20	A
Diode Forward voltage <sup>a</sup>	V <sub>DS</sub>	V <sub>GS</sub> = 0V, I <sub>s</sub> = -4A			-1.2	V
Diode reverse recovery time <sup>b</sup>	t <sub>rr</sub>	I <sub>F</sub> = -4A, dI/dt = 100A/μs			40	ns
Diode reverse recovery charge <sup>b</sup>	Q <sub>rr</sub>				30	nC

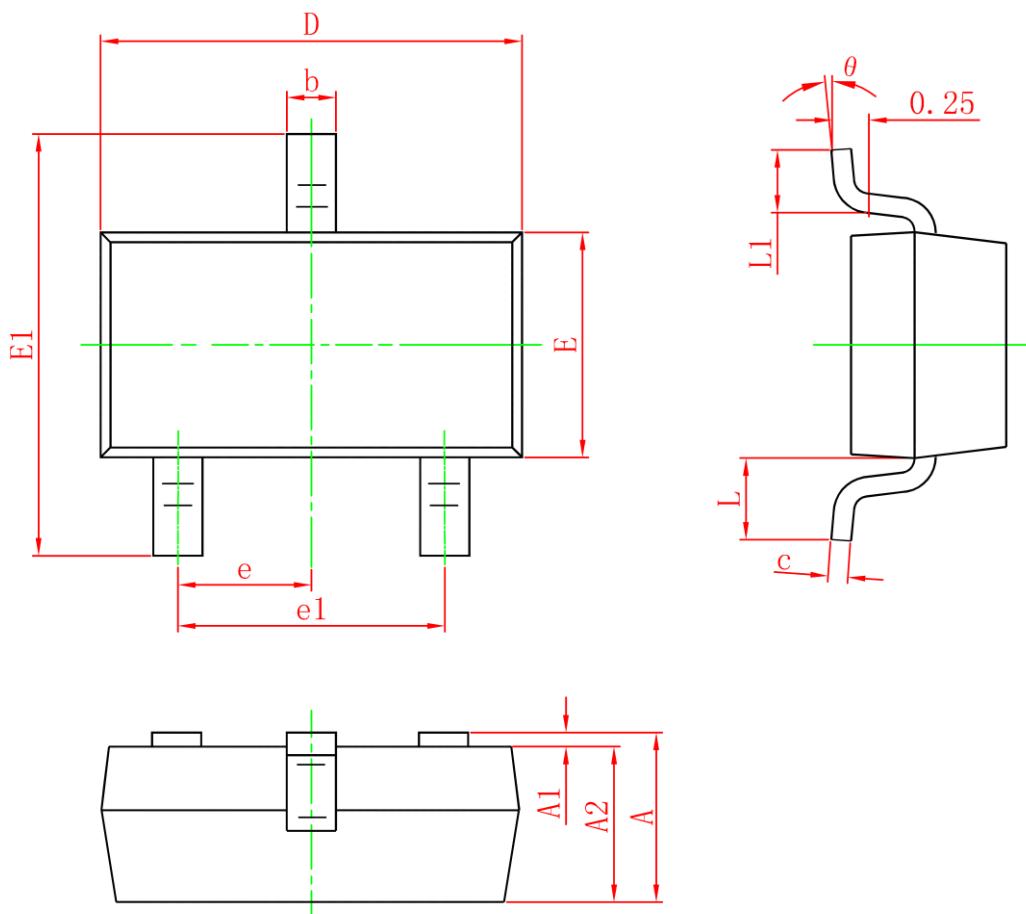
**Notes:**

a. Pulse test; pulse width ≤ 300μs, duty cycle ≤ 2%.

b. Guaranteed by design, not subject to production testing.

## Typical Electrical and Thermal Characteristics

**Output Characteristics**

**Transfer Characteristics**

 $R_{DS(ON)}$  —  $I_D$ 

 $R_{DS(ON)}$  —  $V_{GS}$ 

 $I_S$  —  $V_{SD}$ 

**Threshold Voltage**


**SOT-23 Package Information**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.150	0.035	0.045
A1	0	0.100	0	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.150	1.500	0.045	0.059
E1	2.250	2.650	0.089	0.104
e	0.950TYP		0.037TYP	
e1	1.800	2.000	0.071	0.079
L	0.550REF		0.022REF	
L1	0.300	0.500	0.012	0.020
theta	0°	8°	0°	8°